L Number	Hits	Search Text	DB	Time stamp
1	11677	base and solder and heating	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 16:09
2	3987	372/36,45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 16:10
3	101	die adj3 (bond or bonding) and semiconductor and base and silver adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 16:10
4	3	372/36,45.ccls. and ((die adj3 (bond or bonding) and semiconductor and base and silver adj paste))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 16:12
13	392	semiconductor adj4 thermal adj4 resistance	USPAT; US-PGPUB; EPO; DERWENT	2002/11/06 17:54
14	40	semiconductor adj4 thermal adj4 resistance and paste	USPAT; US-PGPUB; EPO; DERWENT	2002/11/06 17:54
-	11112	die adj3 (bond or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 08:03
-	2269	die adj3 (bond or bonding) and semiconductor and base	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 08:03
-	508	die adj3 (bond or bonding) and semiconductor and base and paste	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 08:04
-	682	372/36.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 08:18
-	21	372/36.ccls. and ((die adj3 (bond or bonding)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 08:27
-	3	372/36.ccls. and ((die adj3 (bond or bonding)) and paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 08:27
-	34	die adj3 (bond or bonding) and surface adj mount adj semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 09:06
-	83	die adj3 (bond or bonding) and surface adj mount adj3 semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/11/06 09:14
-	18	(US-6451628-$ or US-6380620-$ or US-6143590-$ or US-6064111-$ or US-6014318-$ or US-5977633-$ or US-6284570-$ or US-6239012-$ or US-6211462-$ or US-6187611-$ or US-6140696-$ or US-6099678-$ or US-6417024-$ or US-5974066-$ or US-5138428-$).did. or (US-20010011767-$).did. or (EP-905833-$).did. or (EP-400177-$).did.	USPAT; US-PGPUB; EPO; DERWENT	2002/11/06 16:08

C:\APPS\EAST\Workspaces\09 987 010 - 103 Semi laser manuf & Method - SOLDERING.wsp